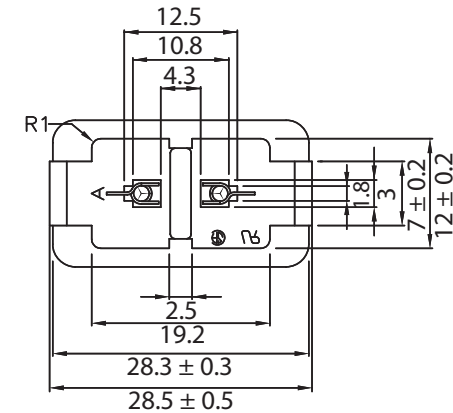
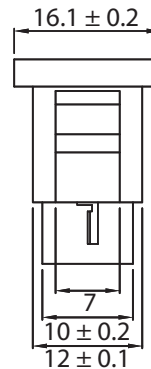
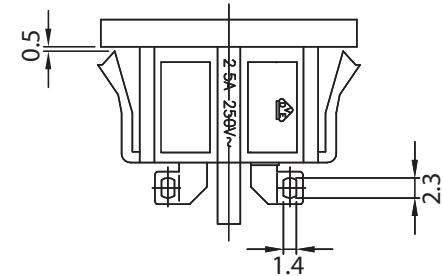
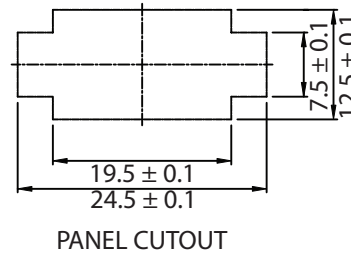
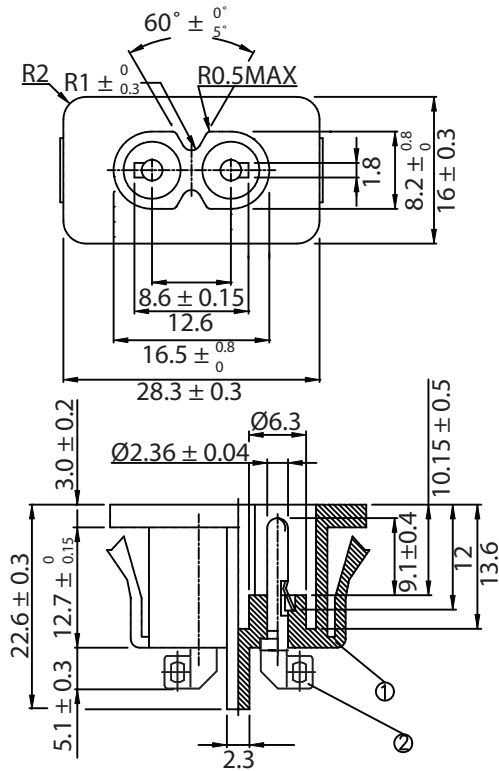


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REVISION			
REV.	DESCRIPTION	DATE	APPROVED
A	Panel Thickness 0.8~1.1	01-28-03	BZ
B	Panel Thickness 0.6~2.0	07-15-03	LG
C	Panel Thickness 0.6~1.5	10-30-03	LG
D	RoHS Compliancy	06-01-06	DP
E	Dimensions Update	09-14-07	DP



CONTROLLED

NOTES:

MATERIAL:

HOUSING: THERMOPLASTIC
 TERMINAL: COPPER ALLOY
 RATING: 2.5A 250V AC
 INSULATION RESISTANCE: OVER 100 OHM, 500V DC
 DIELECTRIC STRENGTH: 2000V AC ONE MINUTE
 APPROVALS: UL,CSA,VDE
 PANEL THICKNESS: 0.6~1.5
 RoHS COMPLIANT

2	Contact PIN Bronze Strip t=0.3mm Tin-Plated	2			
1	Body Insulator PC	1			
Dim range (mm)		Tolerance +/- (mm)		Qualtek Electronics Corp. PPC DIVISION Part Number: 771W-X2/01 RoHS Compliant	
0-1	0.15	1-6	0.20		
6-18	0.30			UNIT: mm	REV. E
18-50	0.50	Drawn / Date	Checked / Date	Approved / Date	
50-120	0.70	B.Zhang	03-10-04	03-10-04	JJH / 03-10-04
120-250	0.90				
250-500	1.20				